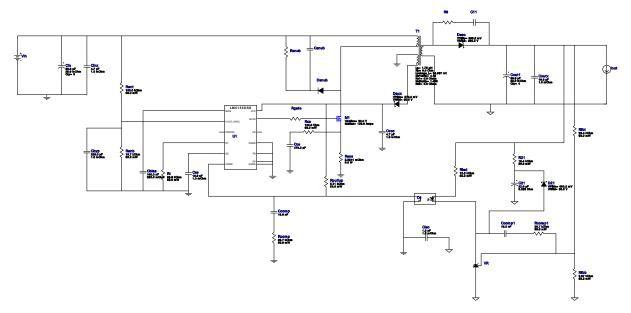


WEBENCH® Design Report

VinMin = 11.0V VinMax = 14.0V Vout = 30.0V lout = 3.0A Device = LM5155DSSR Topology = Flyback Created = 2025-05-23 08:52:54.884 BOM Cost = NA BOM Count = 40 Total Pd = 9.58W

Design: 3 LM5155DSSR LM5155DSSR 14V-22V to 30.00V @ 3A



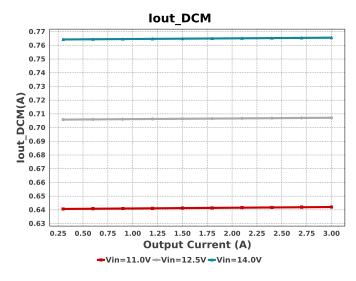
1. Notes: 1. Transformer windings: Np is the primary winding, Ns1 is the secondary winding and Ns2 is the winding for the auxiliary supply. 2. The primary side snubber (Rsnub,Csnub,Dsnub) and secondary side snubber (R9,C11),drive resistor (Rgate) are added as place holders. Kindly refer http://www.ti.com.cn/cn/lit/an/snva744/snva744.pdf for selecting diode for RCD snubber on switch node. Please refer http://www.ti.com/lit/an/slva255/slva255.pdf for design of snubber over the output diode. Hence the overall efficiency displayed is an approximate measure

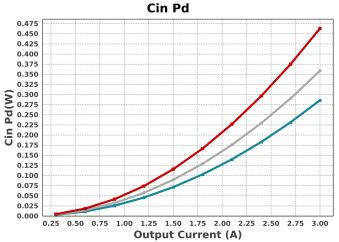
Electrical BOM

Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
C21	Chemi-Con	ELXZ500ELL220MEB5D Series= LXZ	Cap= 22.0 uF ESR= 6.0278 Ohm VDC= 50.0 V IRMS= 155.0 mA	1	\$0.11	Chemi-Con_500x1150 49 mm²
Cbias	AVX	08053C104KAT2A Series= X7R	Cap= 100.0 nF ESR= 280.0 mOhm VDC= 25.0 V IRMS= 0.0 A	1	\$0.01	0805 7 mm ²
Cbyp	MuRata	GRM033R71C221KA01D Series= X7R	Cap= 220.0 pF ESR= 1.0 mOhm VDC= 16.0 V IRMS= 0.0 A	1	\$0.01	0201 2 mm ²
Ccomp	TDK	C2012C0G1H153J085AA Series= C0G/NP0	Cap= 15.0 nF VDC= 50.0 V IRMS= 0.0 A	1	\$0.06	0805 7 mm ²
Ccomp1	TDK	C2012C0G1H153J085AA Series= C0G/NP0	Cap= 15.0 nF VDC= 50.0 V IRMS= 0.0 A	1	\$0.06	0805 7 mm ²
Ccs	Samsung Electro- Mechanics	CL21C471JBANNNC Series= C0G/NP0	Cap= 470.0 pF VDC= 50.0 V IRMS= 0.0 A	1	\$0.01	0805 7 mm ²
Cin	Panasonic	50SVPF39M Series= SVPF	Cap= 39.0 uF ESR= 25.0 mOhm VDC= 50.0 V IRMS= 3.8 A	5	\$1.15	CAPSMT 62 E12 106 mm

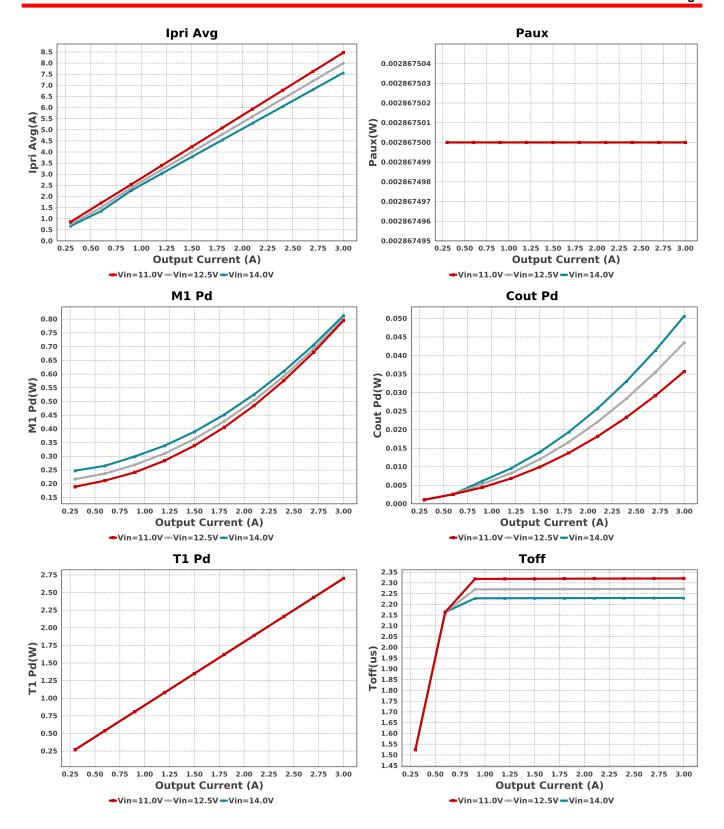
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cinx	CUSTOM	CUSTOM Series= ?	Cap= 4.7 uF ESR= 1.0 mOhm VDC= 18.2 V IRMS= 17.5325 A	1	NA	CUSTOM 0 mm ²
Ciso	Johanson Technology	202R18W102KV4E Series= X7R	Cap= 1.0 nF ESR= 1.0 mOhm VDC= 2.0 kV IRMS= 0.0 A	1	\$0.06	1206_190 11 mm ²
Cout1	Panasonic	50SVPF68M Series= SVPF	Cap= 68.0 uF ESR= 20.0 mOhm VDC= 50.0 V IRMS= 4.3 A	4	\$1.57	CAPSMT_62_F12 151 mm ²
Coutx	MuRata	GRM32ER71J106MA12L Series= X7R	Cap= 10.0 uF ESR= 1.0 mOhm VDC= 63.0 V IRMS= 0.0 A	1	\$0.30	1210_270 15 mm ²
Css	MuRata	GRM033R71A103KA01D Series= X7R	Cap= 10.0 nF ESR= 1.0 mOhm VDC= 10.0 V IRMS= 0.0 A	1	\$0.01	0201 2 mm ²
Cvcc	Taiyo Yuden	TMK212BJ475KG-T Series= X5R	Cap= 4.7 uF ESR= 1.0 mOhm VDC= 25.0 V IRMS= 0.0 A	1	\$0.06	0805 7 mm ²
D21	Panasonic	DB2S31600L	VF@Io= 550.0 mV VRRM= 30.0 V	1	\$0.03	SOD-523 5 mm ²
Daux	Nexperia	PMEG6010CEH,115	VF@Io= 570.0 mV VRRM= 60.0 V	1	\$0.04	SOD-123F 12 mm ²
Dsec	SMC Diode Solutions	SBRD10200TR	VF@Io= 950.0 mV VRRM= 200.0 V	1	\$0.18	DPAK 102 mm ²
M1	Texas Instruments	CSD18532Q5B	VdsMax= 60.0 V IdsMax= 100.0 Amps	1	\$0.73	TRANS_NexFET_Q5B 58 mm²
O1	Vishay-Semiconductor	TCMT1107	Optocoupler	1	\$0.19	SOP-4 44 mm ²
R21	Yageo	RC0201FR-0715K4L Series= ?	Res= 15.4 kOhm Power= 50.0 mW Tolerance= 1.0%	1	\$0.01	0201 2 mm ²
Rcomp	Yageo	RC0201FR-0728K7L Series=?	Res= 28.7 kOhm Power= 50.0 mW Tolerance= 1.0%	1	\$0.01	0201 2 mm ²
Rcomp1	Yageo	RC0201FR-0728K7L Series=?	Res= 28.7 kOhm Power= 50.0 mW Tolerance= 1.0%	1	\$0.01	0201 2 mm ²
Rcs	Vishay-Dale	CRCW0402100RFKED Series= CRCWe3	Res= 100.0 Ohm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm ²
Renb	Yageo	RC0201FR-0718K7L Series=?	Res= 18.7 kOhm Power= 50.0 mW Tolerance= 1.0%	1	\$0.01	0201 2 mm ²
Rent	Vishay-Dale	CRCW0402100KFKED Series= CRCWe3	Res= 100.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm ²
Rfbb	Vishay-Dale	CRCW04022K67FKED Series= CRCWe3	Res= 2.67 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm ²

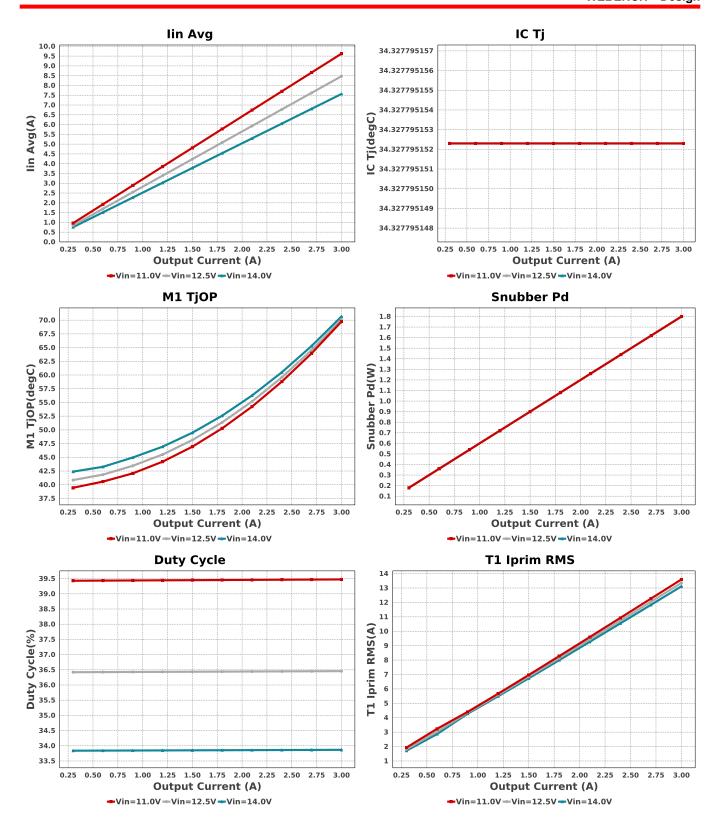
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Rfbt	Vishay-Dale	CRCW040229K4FKED Series= CRCWe3	Res= 29.4 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm ²
Rled	Yageo	RC0201FR-0710KL Series= ?	Res= 10.0 kOhm Power= 50.0 mW Tolerance= 1.0%	1	\$0.01	0201 2 mm ²
Rpullup	Vishay-Dale	CRCW04025K11FKED Series= CRCWe3	Res= 5.11 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm ²
Rsns	CUSTOM	CUSTOM Series= ?	Res= 2.6041 mOhm Power= 0.0 W Tolerance= 0.0%	1	NA	CUSTOM 0 mm ²
Rt	Yageo	RC0201FR-0786K6L Series= ?	Res= 86.6 kOhm Power= 50.0 mW Tolerance= 1.0%	1	\$0.01	0201 2 mm ²
Т1	CUSTOM	CUSTOM	Lp= 1.75 µH Rp= 0.0 Ohm Leakage_L= 34.997 nH Ns1toNp= 4.19 Rs1= 0.0 Ohms Ns2toNp= 1.438 Rs2= 0.0 Ohms	1	NA	CUSTOM 0 mm ²
U1	Texas Instruments	LM5155DSSR	Switcher	1	\$0.69	DSS0012B 12 mm ²
VR	Texas Instruments	TL431IDBVR	Voltage References	1	\$0.05	R-PDSO-G3 16 mm²

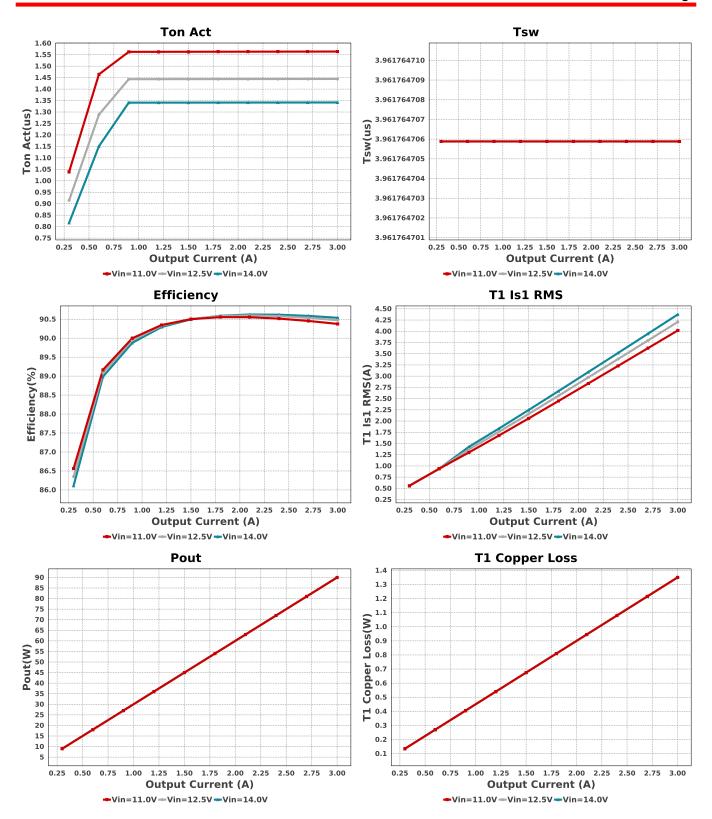


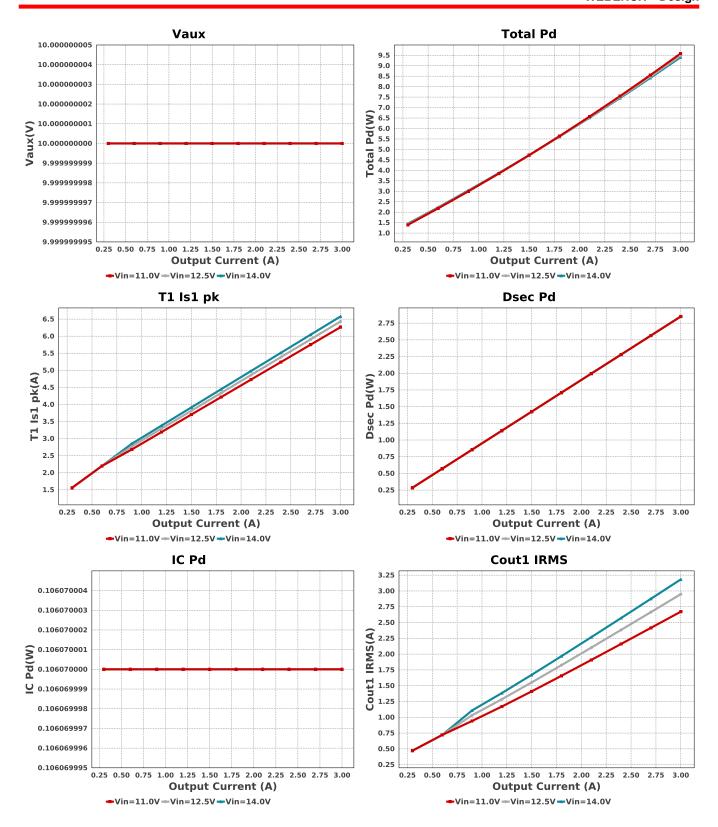


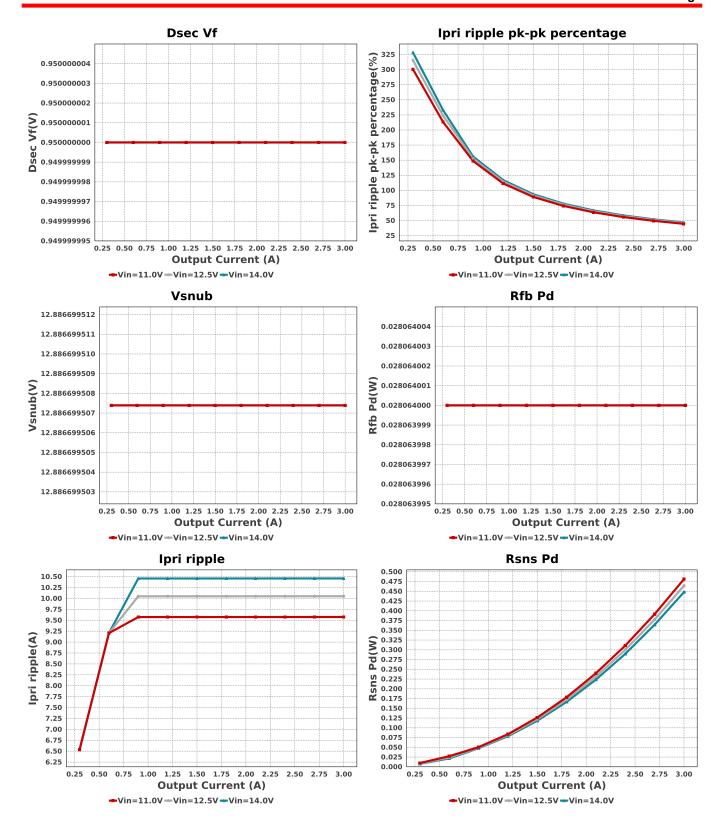
-Vin=11.0V -Vin=12.5V -Vin=14.0V

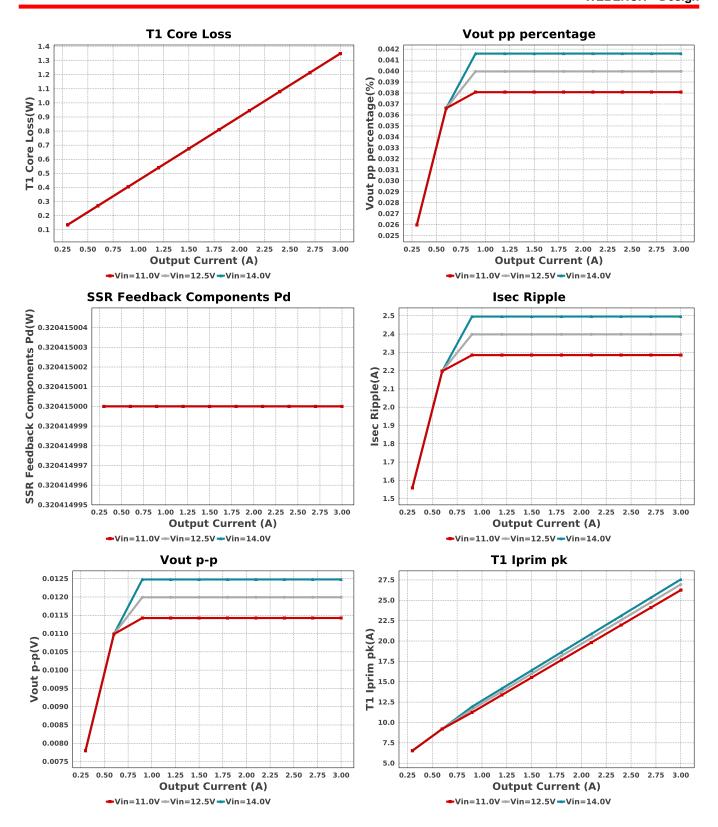


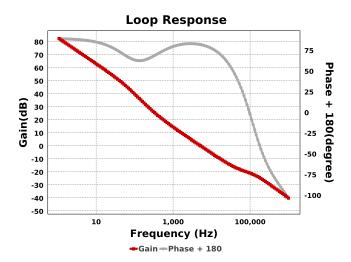












Operating Values

#	Name	Value	Category	Description
1.	Cin Pd	463.27 mW	Capacitor	Input capacitor power dissipation
2.	Cout Pd	35.693 mW	Capacitor	Output capacitor1 power dissipation
2. 3.	Cout 1 IRMS	2.672 A	Capacitor	Output capacitor1 Power dissipation Output capacitor1 RMS ripple current
3. 4.	Dsec Pd	2.85 W	Diode	Secondary Diode Power Dissipation
	Dsec Pa Dsec Vf		Diode	,
5.		950.0 mV		Effective Forward Voltage Drop at the Operating Current
6.	IC Pd	106.07 mW	IC IC	IC power dissipation
	IC Tj	34.328 degC		IC junction temperature
8.	ICThetaJA Effective	40.8 degC/W	IC	Effective IC Junction-to-Ambient Thermal Resistance
9.	lin Avg	9.626 A	IC	Average input current
10.	M1 Pd	794.81 mW	Mosfet	M1 MOSFET total power dissipation
11.	M1 TjOP	69.741 degC	Mosfet	M1 MOSFET junction temperature
	Cin Pd	463.27 mW	Power	Input capacitor power dissipation
13.		35.693 mW	Power	Output capacitor1 power dissipation
14.		2.85 W	Power	Secondary Diode Power Dissipation
	IC Pd	106.07 mW	Power	IC power dissipation
	M1 Pd	794.81 mW	Power	M1 MOSFET total power dissipation
	Paux	2.867 mW	Power	Power Dissipation in Raux and Daux
18.	Rfb Pd	28.064 mW	Power	Rfb Power Dissipation
19.	Rsns Pd	481.26 mW	Power	Current Limit Sense Resistor Power Dissipation
20.	SSR Feedback	320.415 mW	Power	SSR control Mode Feedback Components Power Dissipation.
	Components Pd			
21.	Snubber Pd	1.8 W	Power	Approximate Snubber Power Dissipation (Assumed 2% of Output Power)
22.	T1 Copper Loss	1.35 W	Power	Transformer Copper Loss Power Dissipation
23.	T1 Core Loss	1.35 W	Power	Transformer Core Loss Power Dissipation
24.	T1 Pd	2.7 W	Power	Estimated Losses in Transformer
25.	Total Pd	9.582 W	Power	Total Power Dissipation
26.	Rfb Pd	28.064 mW	Resistor	Rfb Power Dissipation
27.	Rsns Pd	481.26 mW	Resistor	Current Limit Sense Resistor Power Dissipation
28.	BOM Count	40	System Information	Total Design BOM count
29.	Cross Freq	3.673 kHz	System Information	Bode plot crossover frequency
30.	Duty Cycle	39.473 %	System	Duty cycle
24	⊏#ioionov	00 277 0/	Information	Ctandy atata officianay
31.	Efficiency	90.377 %	System	Steady state efficiency
20	Fa at Duint		Information	Total Foot Drint Area of DOM corresponds
32.	FootPrint	1.568 k mm²	System	Total Foot Print Area of BOM components
	_		Information	
33.	Frequency	252.413 kHz	System	Switching frequency
			Information	
34.	Gain Marg	-21.594 dB	System	Bode Plot Gain Margin
			Information	
35.	lout	3.0 A	System	lout operating point
			Information	
36.	lout_DCM	642.052 mA	System	Approximate Current below which DCM mode of operation will begin
	-		Information	
37.	Low Freq Gain	79.022 dB	System	Gain at 1Hz
	- 1		Information	
38.	Mode	CCM	System	Conduction Mode
٠٠.			Information	2

#	Name	Value	Category	Description
39.	Phase Marg	81.94 deg	System Information	Bode Plot Phase Margin
40.	Pout	90.0 W	System Information	Total output power
41.	Toff	2.321 us	System Information	Approximate Converter Off Time
42.	Ton Act	1.564 us	System Information	Approximate Converter On Time
43.	Total BOM	NA	System Information	Total BOM Cost
44.	Tsw	3.962 us	System Information	Switching Time Period
45.	Vin	11.0 V	System Information	Vin operating point
46.	Vout	30.0 V	System Information	Operational Output Voltage
47.	Vout Actual	29.968 V	System Information	Vout Actual calculated based on selected voltage divider resistors
48.	Vout Tolerance	2.913 %	System Information	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
49.	Vout p-p	11.425 mV	System Information	Peak-to-peak output ripple voltage
50.	Vout pp percentage	38.084 m%	System Information	Output Voltage ripple percentage
51.	Vsnub	12.887 V	System Information	Voltage Across the Snubber
52.	Ipri Avg	8.471 A	Transformer	Average Current in Primary Winding over the complete Switching Period
53.	lpri ripple	9.575 A	Transformer	Ripple Current in the Primary Winding
54.	lpri ripple pk-pk percentage	44.617 %	Transformer	Primary Current pk-pk ripple percentage(of lpri avg during ton only)
55.	Isec Ripple	2.285 A	Transformer	Ripple Current in the Secondary Winding
56.	Paux	2.867 mW	Transformer	Power Dissipation in Raux and Daux
57.	T1 Copper Loss	1.35 W	Transformer	Transformer Copper Loss Power Dissipation
58.	T1 Core Loss	1.35 W	Transformer	Transformer Core Loss Power Dissipation
59.	T1 Iprim RMS	13.594 A	Transformer	Transformer Primary RMS Current
60.	T1 Iprim pk	26.248 A	Transformer	Transformer Primary Peak Current
61.	T1 Is1 RMS	4.017 A	Transformer	Transformer Secondary1 RMS Current
62.	T1 ls1 pk	6.264 A	Transformer	Transformer Secondary1 Peak Current
63.	T1 Pd	2.7 W	Transformer	Estimated Losses in Transformer
64.	Vaux	10.0 V	Transformer	Auxiliary Voltage

Design Inputs

Name	Value	Description	
lout	3.0	Maximum Output Current	
VinMax	14.0	Maximum input voltage	
VinMin	11.0	Minimum input voltage	
Vout	30.0	Output Voltage	
base_pn	LM5155	Base Product Number	
source	DC	Input Source Type	
Та	30.0	Ambient temperature	

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

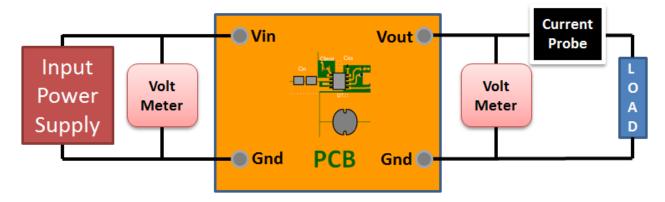
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 11.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum lout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



Design Assistance

- 1. Master key: 29B226842215AB3573FA3854FE6B08E3[v1]
- 2. LM5155 Product Folder: http://www.ti.com/product/LM5155: contains the data sheet and other resources.

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